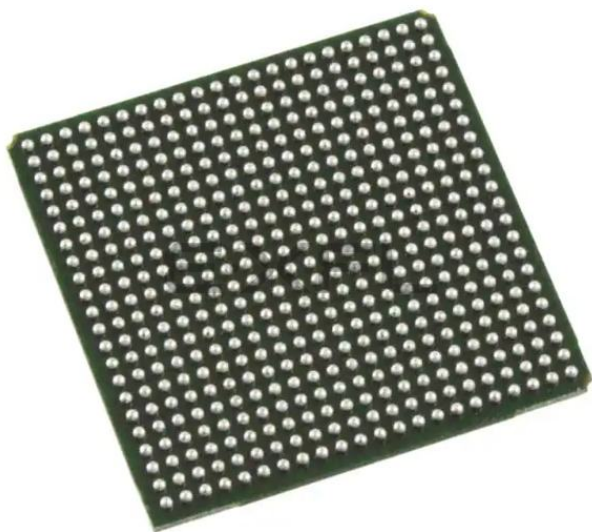




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

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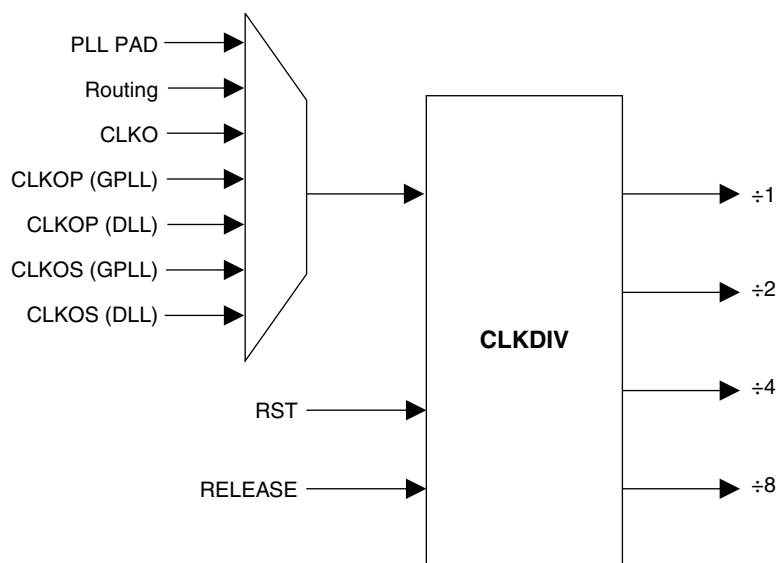
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2625
Number of Logic Elements/Cells	21000
Total RAM Bits	282624
Number of I/O	331
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-20e-5f484c

Figure 2-9. Clock Divider Connections



Clock Distribution Network

LatticeECP2/M devices have eight quadrant-based primary clocks and eight flexible region-based secondary clocks/control signals. Two high performance edge clocks are available on each edge of the device to support high speed interfaces. These clock inputs are selected from external I/Os, the sysCLOCK PLLs, DLLs or routing. These clock inputs are fed throughout the chip via a clock distribution system.

Primary Clock Sources

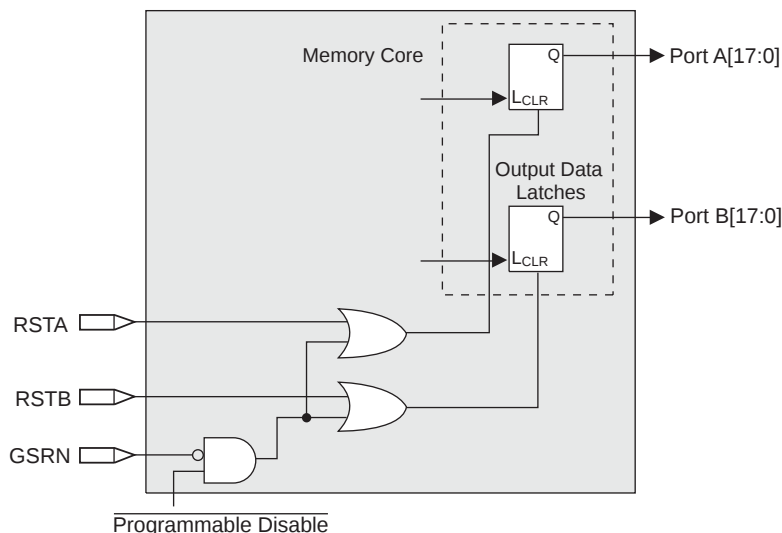
LatticeECP2/M devices derive clocks from five primary sources: PLL (GPLL and SPLL) outputs, DLL outputs, CLK-DIV outputs, dedicated clock inputs and routing. LatticeECP2/M devices have two to eight sysCLOCK PLLs and two DLLs, located on the left and right sides of the device. There are eight dedicated clock inputs, two on each side of the device, with the exception of the LatticeECP2M 256-fpBGA package devices which have six dedicated clock inputs on the device. Figure 2-10 shows the primary clock sources.

2. Write Through – A copy of the input data appears at the output of the same port during a write cycle. This mode is supported for all data widths.

Memory Core Reset

The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously or synchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B, respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-20.

Figure 2-20. Memory Core Reset

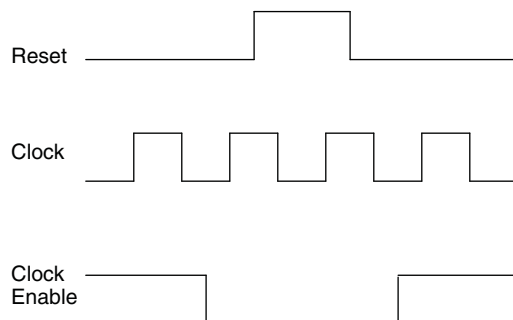


For further information about the sysMEM EBR block, please see the the list of additional technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-21. The GSR input to the EBR is always asynchronous.

Figure 2-21. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

- MULT (Multiply)
- MAC (Multiply, Accumulate)
- MULTADDSUB (Multiply, Addition/Subtraction)
- MULTADDSUBSUM (Multiply, Addition/Subtraction, Accumulate)

The number of elements available on each block depends in the width selected from the three available options x9, x18, and x36. A number of these elements are concatenated for highly parallel implementations of DSP functions. Table 2-7 shows the capabilities of the block.

Table 2-7. Maximum Number of Elements in a Block

Width of Multiply	x9	x18	x36
MULT	8	4	1
MAC	2	2	—
MULTADDSUB	4	2	—
MULTADDSUBSUM	2	1	—

Some options are available in four elements. The input register in all the elements can be directly loaded or can be loaded as a shift register from previous operand registers. By selecting “dynamic operation” the following operations are possible:

- In the ‘Signed/Unsigned’ options the operands can be switched between signed and unsigned on every cycle.
- In the ‘Add/Sub’ option the Accumulator can be switched between addition and subtraction on every cycle.
- The loading of operands can switch between parallel and serial operations.

O standards (together with their supply and reference voltages) supported by LatticeECP2/M devices. For further information about utilizing the sysI/O buffer to support a variety of standards please see the the list of additional technical information at the end of this data sheet.

Table 2-13. Supported Input Standards

Input Standard	V _{REF} (Nom.)	V _{CCIO} ¹ (Nom.)
Single Ended Interfaces		
LVTTL	—	—
LVC MOS33	—	—
LVC MOS25	—	—
LVC MOS18	—	1.8
LVC MOS15	—	1.5
LVC MOS12	—	—
PCI 33	—	3.3
HSTL18 Class I, II	0.9	—
HSTL15 Class I	0.75	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I, II	0.9	—
Differential Interfaces		
Differential SSTL18 Class I, II	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I	—	—
Differential HSTL18 Class I, II	—	—
LVDS, MLVDS, LVPECL, BLVDS, RSDS	—	—

¹ When not specified, V_{CCIO} can be set anywhere in the valid operating range (page 3-1).

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,2}$	Input or I/O Low Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	150	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-210	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	210	μA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	μA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCIO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	210	μA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	-210	μA
V_{BHT}	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{IL} (MAX)$	—	$V_{IH} (MIN)$	V
$C1^4$	I/O Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	8	pf
$C2^4$	Dedicated Input Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	6	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. When used as V_{REF} maximum leakage = 25 μA
3. Applicable to general purpose I/Os in top and bottom banks.
4. T_A 25°C, $f = 1.0MHz$.

LatticeECP2M Initialization Supply Current^{1, 2, 3, 4}
Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ^{5, 6, 7}	Units
I_{CC}	Core Power Supply Current	ECP2M20	41	mA
		ECP2M35	107	mA
		ECP2M50	169	mA
		ECP2M70	254	mA
		ECP2M100	378	mA
I_{CCAUX}	Auxiliary Power Supply Current	ECP2M20	30	mA
		ECP2M35	30	mA
		ECP2M50	30	mA
		ECP2M70	30	mA
		ECP2M100	30	mA
I_{CCGPLL}	GPLL Power Supply Current (per GPLL)	All Devices	0.5	mA
I_{CCSPLL}	SPLL Power Supply Current (per SPLL)	All Devices	0.5	mA
I_{CCIO}	Bank Power Supply Current (per Bank)	All Devices	3	mA
I_{CCJ}	VCCJ Power Supply Current	All Devices	4	mA

1. Until DONE signal is active.

2. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.

3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.

4. Frequency 0MHz.

5. $T_J = 25^{\circ}\text{C}$, power supplies at nominal voltage.

6. A specific configuration pattern is used that scales with the size of the device; consists of 75% PFU utilization, 50% EBR, and 25% I/O configuration.

7. Values shown in this column are the typical average DC current during configuration. Use the Power Calculator tool to find the peak startup current.

LatticeECP2/M Family Timing Adders^{1, 2, 3} (Continued)
Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
HSTL15_I	HSTL_15 class I 4mA drive	-0.22	-0.25	-0.27	ns
HSTL15D_I	Differential HSTL 15 class I 4mA drive	-0.22	-0.25	-0.27	ns
SSTL33_I	SSTL_3 class I	-0.12	-0.15	-0.18	ns
SSTL33_II	SSTL_3 class II	-0.20	-0.23	-0.27	ns
SSTL33D_I	Differential SSTL_3 class I	-0.12	-0.15	-0.18	ns
SSTL33D_II	Differential SSTL_3 class II	-0.20	-0.23	-0.27	ns
SSTL25_I	SSTL_2 class I 8mA drive	-0.16	-0.19	-0.22	ns
SSTL25_II	SSTL_2 class II 16mA drive	-0.19	-0.22	-0.25	ns
SSTL25D_I	Differential SSTL_2 class I 8mA drive	-0.16	-0.19	-0.22	ns
SSTL25D_II	Differential SSTL_2 class II 16mA drive	-0.19	-0.22	-0.25	ns
SSTL18_I	SSTL_1.8 class I	-0.14	-0.17	-0.20	ns
SSTL18_II	SSTL_1.8 class II 8mA drive	-0.20	-0.23	-0.25	ns
SSTL18D_I	Differential SSTL_1.8 class I	-0.14	-0.17	-0.20	ns
SSTL18D_II	Differential SSTL_1.8 class II 8mA drive	-0.20	-0.23	-0.25	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.52	0.60	0.68	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.08	0.09	ns
LVTTTL33_12mA	LVTTTL 12mA drive	0.04	0.04	0.05	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.03	0.02	0.02	ns
LVTTTL33_20mA	LVTTTL 20mA drive	-0.09	-0.09	-0.10	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive, fast slew rate	0.52	0.60	0.68	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive, fast slew rate	0.06	0.08	0.09	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive, fast slew rate	0.04	0.04	0.05	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive, fast slew rate	0.03	0.02	0.02	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive, fast slew rate	-0.09	-0.09	-0.10	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive, fast slew rate	0.41	0.47	0.53	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive, fast slew rate	0.01	0.01	0.00	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive, fast slew rate	0.00	0.00	0.00	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive, fast slew rate	0.04	0.04	0.04	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive, fast slew rate	-0.09	-0.10	-0.11	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive, fast slew rate	0.37	0.40	0.43	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive, fast slew rate	0.10	0.12	0.13	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive, fast slew rate	-0.02	-0.02	-0.02	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive, fast slew rate	-0.02	-0.03	-0.03	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive, fast slew rate	0.29	0.31	0.32	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive, fast slew rate	0.05	0.05	0.06	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive, fast slew rate	0.58	0.69	0.79	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive, fast slew rate	0.13	0.19	0.26	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive, slow slew rate	2.17	2.44	2.71	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive, slow slew rate	2.50	2.67	2.83	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive, slow slew rate	1.72	1.88	2.05	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive, slow slew rate	1.64	1.63	1.62	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive, slow slew rate	1.33	1.36	1.39	ns

LatticeECP2/M Family Timing Adders^{1, 2, 3} (Continued)
Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
LVC MOS25_4mA	LVC MOS 2.5 4mA drive, slow slew rate	2.18	2.26	2.33	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive, slow slew rate	2.19	2.35	2.51	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive, slow slew rate	1.50	1.66	1.82	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive, slow slew rate	1.60	1.59	1.58	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive, slow slew rate	1.43	1.39	1.34	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive, slow slew rate	2.22	2.27	2.32	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive, slow slew rate	1.93	2.08	2.23	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive, slow slew rate	1.43	1.51	1.58	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive, slow slew rate	1.47	1.46	1.45	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive, slow slew rate	2.32	2.38	2.43	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive, slow slew rate	1.84	1.98	2.12	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive, slow slew rate	2.52	2.63	2.74	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive, slow slew rate	1.69	1.83	1.96	ns
PCI33	PCI33	0.04	0.04	0.04	ns

1. Timing Adders are characterized but not tested on every device.

2. LVC MOS timing measured with the load specified in Switching Test Condition table.

3. All other standards tested according to the appropriate specifications.

4. These timing adders are measured with the recommended resistor values.

Timing v.A 0.11

sysCLOCK GPLL Timing

Over Recommended Operating Conditions

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
f _{IN}	Input Clock Frequency (CLKI, CLKFB)	Without external capacitor	20	—	420	MHz
		With external capacitor ^{5, 6}	2	—	420	MHz
f _{OUT}	Output Clock Frequency (CLKOP, CLKOS)	Without external capacitor	20	—	420	MHz
		With external capacitor ⁵	5	—	50	MHz
f _{OUT2}	K-Divider Output Frequency (CLKOK)	Without external capacitor	0.156	—	210	MHz
		With external capacitor ⁵	0.039	—	25	MHz
f _{VCO}	PLL VCO Frequency		640	—	1280	MHz
f _{PFD}	Phase Detector Input Frequency	Without external capacitor	20	—	420	MHz
		With external capacitor ^{5, 6}	2	—	50	MHz
AC Characteristics						
t _{DT}	Output Clock Duty Cycle	Default duty cycle selected ³	45	50	55	%
t _{PH} ⁴	Output Phase Accuracy		—	—	±0.05	UI
t _{OPJIT} ¹	Output Clock Period Jitter	f _{OUT} ≥ 100 MHz	—	—	±125	ps
		50 ≤ f _{OUT} < 100 MHz	—	—	0.025	UIPP
		f _{OUT} < 50 MHz	—	—	0.04	UIPP
t _{SK}	Input Clock to Output Clock Skew	N/M = integer	—	—	±250	ps
t _W	Output Clock Pulse Width	At 90% or 10%	1	—	—	ns
t _{LOCK} ²	PLL Lock-in Time	Without external capacitor	—	—	150	μs
		With external capacitor ⁵	—	—	500	μs
t _{PA}	Programmable Delay Unit		85	130	360	ps
t _{IPJIT}	Input Clock Period Jitter		—	—	±200	ps
t _{FBKDLY}	External Feedback Delay		—	—	10	ns
t _{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t _{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t _{RST}	RST Pulse Width (RESETM/RESETK)		15	—	—	ns
	Reset Signal Pulse Width (CNTRST)	Without external capacitor	500	—	—	ns
		With external capacitor ⁵	20	—	—	μs

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock and no additional I/O pins toggling.

2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.

3. Using LVDS output buffers.

4. Relative to CLKOP.

5. Value of external capacitor: 5.6 nF ±20%, NPO dielectric, ceramic chip capacitor, 1206 or smaller package, connected to PLLCAP pin.

6. $f_{OUT} (max) = f_{IN} * 10$ for $f_{IN} < 5$ MHz.

LatticeECP2/M sysCONFIG Port Timing Specifications (Continued)

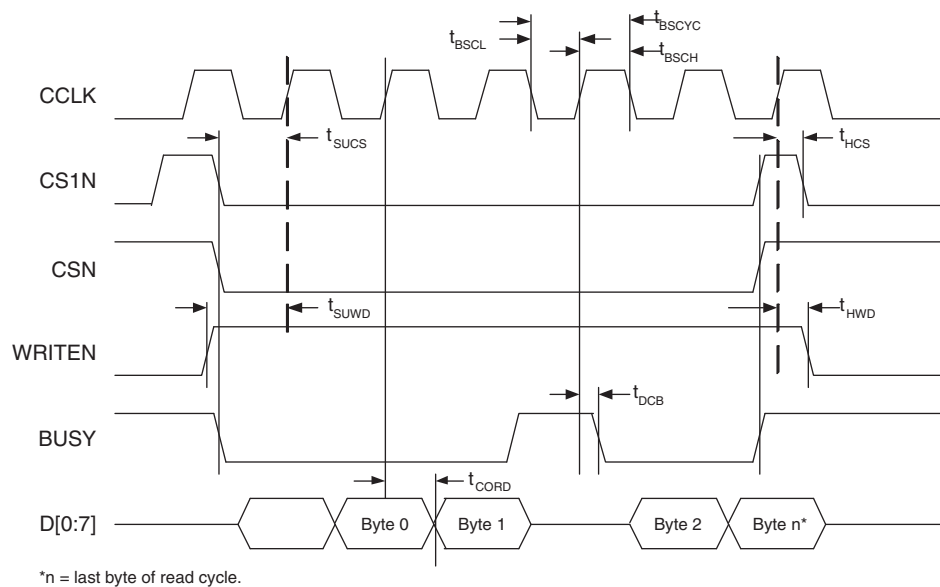
Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
f_{MAXSPI}	Max. CCLK Frequency - SPI Flash Read Opcode (0x03) (SPIFASTN = 1)	—	20	MHz
	Max. CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN = 0)	—	50	MHz
	Max. CCLK Frequency - Encrypted Bitstream	—	10	MHz
t_{SUSPI}	SOSPI Data Setup Time Before CCLK	7	—	ns
t_{HSPI}	SOSPI Data Hold Time After CCLK	2	—	ns
t_{SUMCDI}	DI Setup to CCLK	7	—	ns
t_{HMCDI}	DI Hold from CCLK	1	—	ns

1. Re-toggling the PROGRAMN pin is not permitted until the INITN pin is high. Avoid consecutive toggling of the PROGRAMN.
2. For SED (Soft Error Detect), the SEDCLKIN operating frequency must be at least 20MHz. SEDCLKIN is derived from Master Clock Frequency that has a +/-30% variation..

Parameter	Min.	Max.	Units
Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
Duty Cycle	40	60	%

Figure 3-14. sysCONFIG Parallel Port Read Cycle



LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 144 TQFP (Cont.)

LFE2-6E/SE					LFE2-12E/12SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
136	PT6B	0		C	PT16B	0		C
137	PT6A	0		T	PT16A	0		T
138	GND	-			GND	-		
139	VCCIO0	0			VCCIO0	0		
140	PT4B	0		C	PT6B	0		C
141	PT4A	0		T	PT6A	0		T
142	VCCAUX	-			VCCAUX	-		
143	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C
144	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one-to-one connection with a package ball or pin.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA14	PB35B	4	BDQ33	C	PB44B	4	BDQ42	C
W13	PB37A	4	BDQ33	T	PB46A	4	BDQ42	T
GNDIO	GNDIO4	-			GNDIO4	-		
W14	PB37B	4	BDQ33	C	PB46B	4	BDQ42	C
AB18	PB39A	4	BDQ42	T	PB48A	4	BDQ51	T
AB19	PB39B	4	BDQ42	C	PB48B	4	BDQ51	C
Y15	PB41A	4	BDQ42	T	PB50A	4	BDQ51	T
V14	PB40A	4	BDQ42	T	PB49A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
AA15	PB41B	4	BDQ42	C	PB50B	4	BDQ51	C
W15	PB40B	4	BDQ42	C	PB49B	4	BDQ51	C
GNDIO	GNDIO4	-			GNDIO	-		
AB20	PB43A	4	BDQ42	T	PB52A	4	BDQ51	T
AA16	PB42A	4	BDQS42	T	PB51A	4	BDQS51	T
AB21	PB43B	4	BDQ42	C	PB52B	4	BDQ51	C
AA17	PB42B	4	BDQ42	C	PB51B	4	BDQ51	C
Y16	PB45A	4	BDQ42	T	PB54A	4	BDQ51	T
U15	PB44A	4	BDQ42	T	PB53A	4	BDQ51	T
VCCIO	VCCIO4	4			VCCIO4	4		
W16	PB45B	4	BDQ42	C	PB54B	4	BDQ51	C
U16	PB44B	4	BDQ42	C	PB53B	4	BDQ51	C
AA18	PB46A	4	BDQ42	T	PB55A	4	BDQ51	T
AA20	PB46B	4	BDQ42	C	PB55B	4	BDQ51	C
GNDIO	GNDIO4	-			GNDIO	-		
V16	PB49A	4	BDQ51	T	PB58A	4	BDQ60	T
V17	PB49B	4	BDQ51	C	PB58B	4	BDQ60	C
AA21	PB48A	4	BDQ51	T	PB57A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
Y19	PB51A	4	BDQS51	T	PB60A	4	BDQS60	T
AA22	PB48B	4	BDQ51	C	PB57B	4	BDQ60	C
Y20	PB51B	4	BDQ51	C	PB60B	4	BDQ60	C
Y18	PB50A	4	BDQ51	T	PB59A	4	BDQ60	T
GNDIO	GNDIO4	-			GNDIO4	-		
Y21	PB53A	4	BDQ51	T	PB62A	4	BDQ60	T
Y17	PB50B	4	BDQ51	C	PB59B	4	BDQ60	C
Y22	PB53B	4	BDQ51	C	PB62B	4	BDQ60	C
W17	PB52A	4	BDQ51	T	PB61A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
U18	PB54A	4	BDQ51	T	PB63A	4	BDQ60	T
W18	PB52B	4	BDQ51	C	PB61B	4	BDQ60	C
V18	PB54B	4	BDQ51	C	PB63B	4	BDQ60	C
GNDIO	GNDIO4	-			GNDIO4	-		
T15	PB55A	4	VREF2_4/BDQ51	T	PB64A	4	VREF2_4/BDQ60	T
T16	PB55B	4	VREF1_4/BDQ51	C	PB64B	4	VREF1_4/BDQ60	C

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K8	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L12	GND	-			GND	-		
L13	GND	-			GND	-		
L15	GND	-			GND	-		
L8	GND	-			GND	-		
M10	GND	-			GND	-		
M11	GND	-			GND	-		
M12	GND	-			GND	-		
M13	GND	-			GND	-		
M15	GND	-			GND	-		
M8	GND	-			GND	-		
N10	GND	-			GND	-		
N11	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N15	GND	-			GND	-		
N8	GND	-			GND	-		
P14	GND	-			GND	-		
P20	GND	-			GND	-		
P3	GND	-			GND	-		
P9	GND	-			GND	-		
R10	GND	-			GND	-		
R11	GND	-			GND	-		
R12	GND	-			GND	-		
R13	GND	-			GND	-		
U17	GND	-			GND	-		
U6	GND	-			GND	-		
W2	GND	-			GND	-		
W21	GND	-			GND	-		
Y14	GND	-			GND	-		
Y9	GND	-			GND	-		
A1	GND	-			GND	-		
N18	VCCPLL	-			VCCPLL	-		
K6	NC	-			VCCPLL	-		
N6	VCCPLL	-			VCCPLL	-		
J16	NC	-			VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
Y21	PB64A	4	VREF2_4/BDQ60	T	PB73A	4	VREF2_4/BDQ69	T	
AB23	PB64B	4	VREF1_4/BDQ60	C	PB73B	4	VREF1_4/BDQ69	C	
GND	GNDIO4	-			GNDIO4	-			
AD24	CFG2	8			CFG2	8			
W20	CFG1	8			CFG1	8			
AC24	CFG0	8			CFG0	8			
V19	PROGRAMN	8			PROGRAMN	8			
AA22	CCLK	8			CCLK	8			
AB24	INITN	8			INITN	8			
AD25	DONE	8			DONE	8			
GND	GNDIO8	-			GNDIO8	-			
W21	PR44B	8	WRITEN	C	PR58B	8	WRITEN	C	
Y22	PR44A	8	CS1N	T	PR58A	8	CS1N	T	
AC25	PR43B	8	CSN	C	PR57B	8	CSN	C	
AB25	PR43A	8	D0/SPIFASTN	T	PR57A	8	D0/SPIFASTN	T	
VCCIO	VCCIO8	8			VCCIO8	8			
AD26	PR42B	8	D1	C	PR56B	8	D1	C	
AC26	PR42A	8	D2	T	PR56A	8	D2	T	
Y23	PR41B	8	D3	C	PR55B	8	D3	C	
GND	GNDIO8	-			GNDIO8	-			
W22	PR41A	8	D4	T	PR55A	8	D4	T	
AA25	PR40B	8	D5	C	PR54B	8	D5	C	
AB26	PR40A	8	D6	T	PR54A	8	D6	T	
W23	PR39B	8	D7/SPID0	C	PR53B	8	D7/SPID0	C	
VCCIO	VCCIO8	8			VCCIO8	8			
V22	PR39A	8	DI/CSSPI0N	T	PR53A	8	DI/CSSPI0N	T	
Y24	PR38B	8	DOU/CSON	C	PR52B	8	DOU/CSON	C	
Y25	PR38A	8	BUSY/SISPI	T	PR52A	8	BUSY/SISPI	T	
W24	PR37B	3	RDQ34	C	PR51B	3	RDQ48	C	
GND	GNDIO3	-			GNDIO3	-			
V23	PR37A	3	RDQ34	T	PR51A	3	RDQ48	T	
AA26	PR36B	3	RDQ34	C (LVDS)*	PR50B	3	RDQ48	C (LVDS)*	
Y26	PR36A	3	RDQ34	T (LVDS)*	PR50A	3	RDQ48	T (LVDS)*	
U21	PR35B	3	RDQ34	C	PR49B	3	RDQ48	C	
VCCIO	VCCIO3	3			VCCIO3	3			
U19	PR35A	3	RDQ34	T	PR49A	3	RDQ48	T	
W25	PR34B	3	RDQ34	C (LVDS)*	PR48B	3	RDQ48	C (LVDS)*	
W26	PR34A	3	RDQS34	T (LVDS)*	PR48A	3	RDQS48	T (LVDS)*	
GND	GNDIO3	-			GNDIO3	-			
V24	PR33B	3	RDQ34	C	PR47B	3	RDQ48	C	
V25	PR33A	3	RDQ34	T	PR47A	3	RDQ48	T	
V26	PR32B	3	RDQ34	C (LVDS)*	PR46B	3	RDQ48	C (LVDS)*	
U26	PR32A	3	RDQ34	T (LVDS)*	PR46A	3	RDQ48	T (LVDS)*	
VCCIO	VCCIO3	3			VCCIO3	3			
U22	PR31B	3	RLM0_GPLL_C_FB_A/RDQ34	C	PR45B	3	RLM0_GPLL_C_FB_A/RDQ48	C	
U23	PR31A	3	RLM0_GPLL_T_FB_A/RDQ34	T	PR45A	3	RLM0_GPLL_T_FB_A/RDQ48	T	

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
K1	PL27B	7	LDQ29	C (LVDS)*
K5	PL28A	7	LDQ29	T
K7	PL28B	7	LDQ29	C
GND	GNDIO7	-		
K4	PL29A	7	LDQS29	T (LVDS)*
K3	PL29B	7	LDQ29	C (LVDS)*
L8	PL30A	7	LDQ29	T
VCCIO	VCCIO7	7		
L6	PL30B	7	LDQ29	C
L2	PL31A	7	LDQ29	T (LVDS)*
L1	PL31B	7	LDQ29	C (LVDS)*
L7	PL32A	7	LDQ29	T
GND	GNDIO7	-		
L5	PL32B	7	LDQ29	C
L4	PL33A	7	LDQ37	T (LVDS)*
L3	PL33B	7	LDQ37	C (LVDS)*
M8	PL34A	7	LDQ37	T
M6	PL34B	7	LDQ37	C
VCCIO	VCCIO7	7		
M2	PL35A	7	LDQ37	T (LVDS)*
M1	PL35B	7	LDQ37	C (LVDS)*
M7	PL36A	7	LDQ37	T
M5	PL36B	7	LDQ37	C
GND	GNDIO7	-		
M4	PL37A	7	LDQS37	T (LVDS)*
M3	PL37B	7	LDQ37	C (LVDS)*
N6	PL38A	7	LUM0_SPLLT_IN_A/LDQ37	T
VCCIO	VCCIO7	7		
N8	PL38B	7	LUM0_SPLLC_IN_A/LDQ37	C
N5	PL39A	7	LUM0_SPLLT_FB_A/LDQ37	T
N7	PL39B	7	LUM0_SPLLC_FB_A/LDQ37	C
GND	GNDIO7	-		
VCCIO	VCCIO7	7		
T9	PL50A	7	LDQ54	
R9	PL51A	7	LDQ54	T
P7	PL51B	7	LDQ54	C
VCCIO	VCCIO7	7		
N2	PL52A	7	LDQ54	T (LVDS)*
N1	PL52B	7	LDQ54	C (LVDS)*
P6	PL53A	7	LDQ54	T
P5	PL53B	7	LDQ54	C
GND	GNDIO7	-		
P4	PL54A	7	LDQS54	T (LVDS)*

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
Y10	VCC	-		
Y11	VCC	-		
Y12	VCC	-		
Y13	VCC	-		
Y18	VCC	-		
Y19	VCC	-		
Y20	VCC	-		
J13	VCCIO0	0		
J14	VCCIO0	0		
K12	VCCIO0	0		
K13	VCCIO0	0		
K14	VCCIO0	0		
K15	VCCIO0	0		
J17	VCCIO1	1		
J18	VCCIO1	1		
J20	VCCIO1	1		
K17	VCCIO1	1		
K18	VCCIO1	1		
K20	VCCIO1	1		
L21	VCCIO2	2		
M21	VCCIO2	2		
M22	VCCIO2	2		
N21	VCCIO2	2		
N22	VCCIO2	2		
R21	VCCIO2	2		
U21	VCCIO3	3		
U22	VCCIO3	3		
V21	VCCIO3	3		
V22	VCCIO3	3		
W21	VCCIO3	3		
Y22	VCCIO3	3		
AA16	VCCIO4	4		
AA17	VCCIO4	4		
AA18	VCCIO4	4		
AA19	VCCIO4	4		
AB17	VCCIO4	4		
AB18	VCCIO4	4		
AA12	VCCIO5	5		
AA13	VCCIO5	5		
AA14	VCCIO5	5		
AB12	VCCIO5	5		
AB13	VCCIO5	5		
AB14	VCCIO5	5		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
K19	PR16A	2	RDQ15	T	PR19A	2		T	
G24	PR15B	2	RDQ15	C (LVDS)*	PR18B	2		C*	
G23	PR15A	2	RDQS15	T (LVDS)*	PR18A	2		T*	
GNDIO	GNDIO2	-			GNDIO2	-			
J18	PR14B	2	RDQ15	C	PR14B	2		C	
F22	PR14A	2	RDQ15	T	PR14A	2		T	
-	-	-			VCCIO2	2			
F23	PR13B	2	RDQ15	C (LVDS)*	PR13B	2		C*	
F24	PR13A	2	RDQ15	T (LVDS)*	PR13A	2		T*	
VCCIO	VCCIO2	2			-	-			
H20	PR12B	2	RUM0_SPLLC_FB_A/RDQ15	C	PR12B	2	RUM0_SPLLC_FB_A	C	
-	-	-			GNDIO2	-			
F21	PR12A	2	RUM0_SPLLT_FB_A/RDQ15	T	PR12A	2	RUM0_SPLLT_FB_A	T	
G26	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C (LVDS)*	PR11B	2	RUM0_SPLLC_IN_A	C*	
F26	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*	PR11A	2	RUM0_SPLLT_IN_A	T*	
-	-	-			VCCIO2	2			
E24	PR9B	2	VREF2_2	C	PR9B	2	VREF2_2	C	
GNDIO	GNDIO2	-			GNDIO2	-			
E23	PR9A	2	VREF1_2	T	PR9A	2	VREF1_2	T	
VCCIO	VCCIO4	4			VCCIO2	2			
H19	XRES	-			XRES	-			
C25	URC_SQ_VCCRX0	12			URC_SQ_VCCRX0	12			
A24	URC_SQ_HDINP0	12		T	URC_SQ_HDINP0	12		T	
B25	URC_SQ_VCCIB0	12			URC_SQ_VCCIB0	12			
B24	URC_SQ_HDINN0	12		C	URC_SQ_HDINN0	12		C	
C22	URC_SQ_VCCTX0	12			URC_SQ_VCCTX0	12			
A21	URC_SQ_HDOUTP0	12		T	URC_SQ_HDOUTP0	12		T	
A22	URC_SQ_VCCOB0	12			URC_SQ_VCCOB0	12			
B21	URC_SQ_HDOUTN0	12		C	URC_SQ_HDOUTN0	12		C	
C21	URC_SQ_VCCTX1	12			URC_SQ_VCCTX1	12			
B20	URC_SQ_HDOUTN1	12		C	URC_SQ_HDOUTN1	12		C	
C20	URC_SQ_VCCOB1	12			URC_SQ_VCCOB1	12			
A20	URC_SQ_HDOUTP1	12		T	URC_SQ_HDOUTP1	12		T	
C24	URC_SQ_VCCRX1	12			URC_SQ_VCCRX1	12			
B23	URC_SQ_HDINN1	12		C	URC_SQ_HDINN1	12		C	
C23	URC_SQ_VCCIB1	12			URC_SQ_VCCIB1	12			
A23	URC_SQ_HDINP1	12		T	URC_SQ_HDINP1	12		T	
B19	URC_SQ_VCCAUX33	12			URC_SQ_VCCAUX33	12			
E19	URC_SQ_REFCLKN	12		C	URC_SQ_REFCLKN	12		C	
D19	URC_SQ_REFCLKP	12		T	URC_SQ_REFCLKP	12		T	
C19	URC_SQ_VCCP	12			URC_SQ_VCCP	12			
A15	URC_SQ_HDINP2	12		T	URC_SQ_HDINP2	12		T	

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5F484C	331	1.2V	-5	fpBGA	484	COM	35
LFE2-35E-6F484C	331	1.2V	-6	fpBGA	484	COM	35
LFE2-35E-7F484C	331	1.2V	-7	fpBGA	484	COM	35
LFE2-35E-5F672C	450	1.2V	-5	fpBGA	672	COM	35
LFE2-35E-6F672C	450	1.2V	-6	fpBGA	672	COM	35
LFE2-35E-7F672C	450	1.2V	-7	fpBGA	672	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5F484C	339	1.2V	-5	fpBGA	484	COM	50
LFE2-50E-6F484C	339	1.2V	-6	fpBGA	484	COM	50
LFE2-50E-7F484C	339	1.2V	-7	fpBGA	484	COM	50
LFE2-50E-5F672C	500	1.2V	-5	fpBGA	672	COM	50
LFE2-50E-6F672C	500	1.2V	-6	fpBGA	672	COM	50
LFE2-50E-7F672C	500	1.2V	-7	fpBGA	672	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5F672C	500	1.2V	-5	fpBGA	672	COM	70
LFE2-70E-6F672C	500	1.2V	-6	fpBGA	672	COM	70
LFE2-70E-7F672C	500	1.2V	-7	fpBGA	672	COM	70
LFE2-70E-5F900C	583	1.2V	-5	fpBGA	900	COM	70
LFE2-70E-6F900C	583	1.2V	-6	fpBGA	900	COM	70
LFE2-70E-7F900C	583	1.2V	-7	fpBGA	900	COM	70

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5T144I	90	1.2V	-5	TQFP	144	IND	6
LFE2-6E-6T144I	90	1.2V	-6	TQFP	144	IND	6
LFE2-6E-5F256I	190	1.2V	-5	fpBGA	256	IND	6
LFE2-6E-6F256I	190	1.2V	-6	fpBGA	256	IND	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5T144I	93	1.2V	-5	TQFP	144	IND	12
LFE2-12E-6T144I	93	1.2V	-6	TQFP	144	IND	12
LFE2-12E-5Q208I	131	1.2V	-5	PQFP	208	IND	12
LFE2-12E-6Q208I	131	1.2V	-6	PQFP	208	IND	12
LFE2-12E-5F256I	193	1.2V	-5	fpBGA	256	IND	12
LFE2-12E-6F256I	193	1.2V	-6	fpBGA	256	IND	12
LFE2-12E-5F484I	297	1.2V	-5	fpBGA	484	IND	12
LFE2-12E-6F484I	297	1.2V	-6	fpBGA	484	IND	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100E-5F1152C	520	1.2V	-5	fpBGA	1152	COM	100
LFE2M100E-6F1152C	520	1.2V	-6	fpBGA	1152	COM	100
LFE2M100E-7F1152C	520	1.2V	-7	fpBGA	1152	COM	100
LFE2M100E-5F900C	416	1.2V	-5	fpBGA	900	COM	100
LFE2M100E-6F900C	416	1.2V	-6	fpBGA	900	COM	100
LFE2M100E-7F900C	416	1.2V	-7	fpBGA	900	COM	100

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M20SE-5FN484I	304	1.2V	-5	Lead-Free fpBGA	484	Ind	20
LFE2M20SE-6FN484I	304	1.2V	-6	Lead-Free fpBGA	484	Ind	20
LFE2M20SE-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	Ind	20
LFE2M20SE-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	Ind	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M35SE-5FN672I	410	1.2V	-5	Lead-Free fpBGA	672	Ind	35
LFE2M35SE-6FN672I	410	1.2V	-6	Lead-Free fpBGA	672	Ind	35
LFE2M35SE-5FN484I	303	1.2V	-5	Lead-Free fpBGA	484	Ind	35
LFE2M35SE-6FN484I	303	1.2V	-6	Lead-Free fpBGA	484	Ind	35
LFE2M35SE-5FN256I	140	1.2V	-5	Lead-Free fpBGA	256	Ind	35
LFE2M35SE-6FN256I	140	1.2V	-6	Lead-Free fpBGA	256	Ind	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M50SE-5FN900I	410	1.2V	-5	Lead-Free fpBGA	900	Ind	50
LFE2M50SE-6FN900I	410	1.2V	-6	Lead-Free fpBGA	900	Ind	50
LFE2M50SE-5FN672I	372	1.2V	-5	Lead-Free fpBGA	672	Ind	50
LFE2M50SE-6FN672I	372	1.2V	-6	Lead-Free fpBGA	672	Ind	50
LFE2M50SE-5FN484I	270	1.2V	-5	Lead-Free fpBGA	484	Ind	50
LFE2M50SE-6FN484I	270	1.2V	-6	Lead-Free fpBGA	484	Ind	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M70SE-5FN1152I	436	1.2V	-5	Lead-Free fpBGA	1152	Ind	70
LFE2M70SE-6FN1152I	436	1.2V	-6	Lead-Free fpBGA	1152	Ind	70
LFE2M70SE-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	70
LFE2M70SE-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	70

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2M100SE-5FN1152I	520	1.2V	-5	Lead-Free fpBGA	1152	Ind	100
LFE2M100SE-6FN1152I	520	1.2V	-6	Lead-Free fpBGA	1152	Ind	100
LFE2M100SE-5FN900I	416	1.2V	-5	Lead-Free fpBGA	900	Ind	100
LFE2M100SE-6FN900I	416	1.2V	-6	Lead-Free fpBGA	900	Ind	100